

3GPP TSG RAN#8
Dusseldorf, Germany, 21 -23 June, 2000

RP (00)0316

Agenda Item: 6

Source: CWTS

To: RAN#8

Title: Proposed WI " Low chip rate TDD UTRAN architecture aspects"

Document for: Approval

Work Item Description

Title

Low chip rate TDD UTRAN architecture aspects

1 3GPP Work Area

X	Radio Access
	Core Network
	Services

2 Linked work items

Low Chip Rate TDD physical layer

Low chip rate TDD layer2 and layer3 protocol aspects

Smart Antenna

RF Radio Transmission/Reception, System Performance Requirements and Conformance Testing

Low chip rate TDD UE radio access capabilities

3 Justification

The integration of TDD low chip rate option in Release 2000 is discussed and approved in RAN#6. The work plan of the integration of low chip rate TDD in R00 was discussed in RAN#7. As a feature, the low chip rate TDD is sub-divided into several building blocks via the email discussion. In Iub and Iur interfaces, especially, low chip rate TDD will result in adaptations of Information Elements in radio link related signaling, to support the changed physical channel parameters. In addition, low chip rate TDD should define some procedures which are different from those of UTRA TDD to provide services such as location services, beamforming, and uplink synchronisation. This paper is to describe one of the low chip rate TDD building blocks – UTRAN architecture aspects

4 Objective

- For UTRAN architecture aspects, it includes the following work tasks:
 - Iub aspects
 - Iur aspects

Task	Planned Start	Planned Finish
prepare technical inputs	06/2000	09/2000
drafting CR's and possible new specs	09/2000	12/2000

5 Service Aspects

None

6 MMI-Aspects

None

7 Charging Aspects

None

8 Security Aspects

None

9 Impacts

Affects :	USIM	ME	AN	CN	Others
Yes			X		
No	X	X		X	X
Don't know					

10 Expected Output and Time scale (to be updated at each plenary)

New specifications						
Spec No.	Title	Prime rsp. WG	2ndary rsp. WG(s)	Presented for information at plenary#	Approved at plenary#	Comments
Affected existing specifications						
Spec No.	CR	Subject			Approved at plenary#	Comments
25.401		UTRAN Overall Description			RAN#10	
25.402		Synchronisation in UTRAN Stage 2			RAN#10	
25.433		UTRAN Iub Interface NBAP Signalling			RAN#10	
25.423		UTRAN Iur Interface RNSAP Signalling			RAN#10	
25.427		UTRAN Iub/Iur Interface User Plane Protocols for DCH data streams			RAN#10	
25.435		UTRAN Iub Interface User Plane Protocols for Common Transport Channel data streams			RAN#10	

11 Work item rapporteurs

Mr. Yanhui Liu (CATT/CWTS)

12 Work item leadership

RAN WG3

13 Supporting Companies

Ericsson, Fujitsu, IDC, LG, NTT DoCoMo, Panasonic, RFI, Samsung, Siemens

14 Classification of the WI (if known)

	Feature (go to 14a)
X	Building Block (go to 14b)
	Work Task (go to 14c)

14a The WI is a Feature: List of building blocks under this feature

(list of Work Items identified as building blocks)

14b The WI is a Building Block: parent Feature

low chip rate TDD

14c The WI is a Work Task: parent Building Block

(one Work Item identified as a building block)